

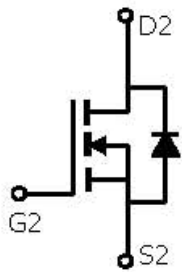
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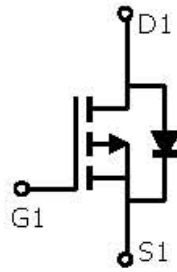
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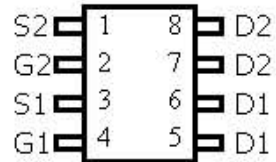
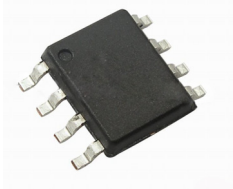
DC/DC



n-channel



p-channel





	°C				
	°C				
	∞				

N-

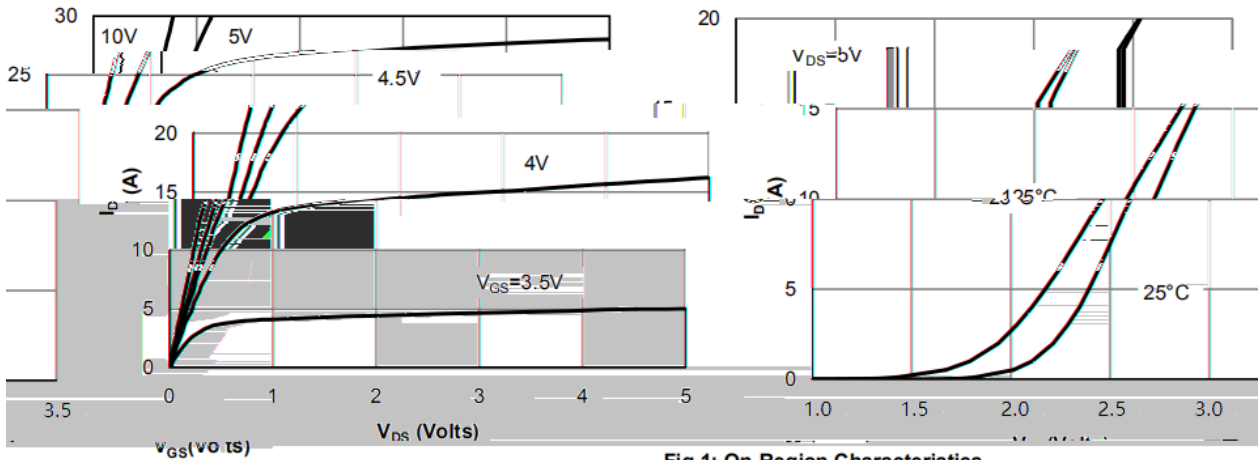


Figure 2: Transfer Characteristics

Fig 1: On-Region Characteristics

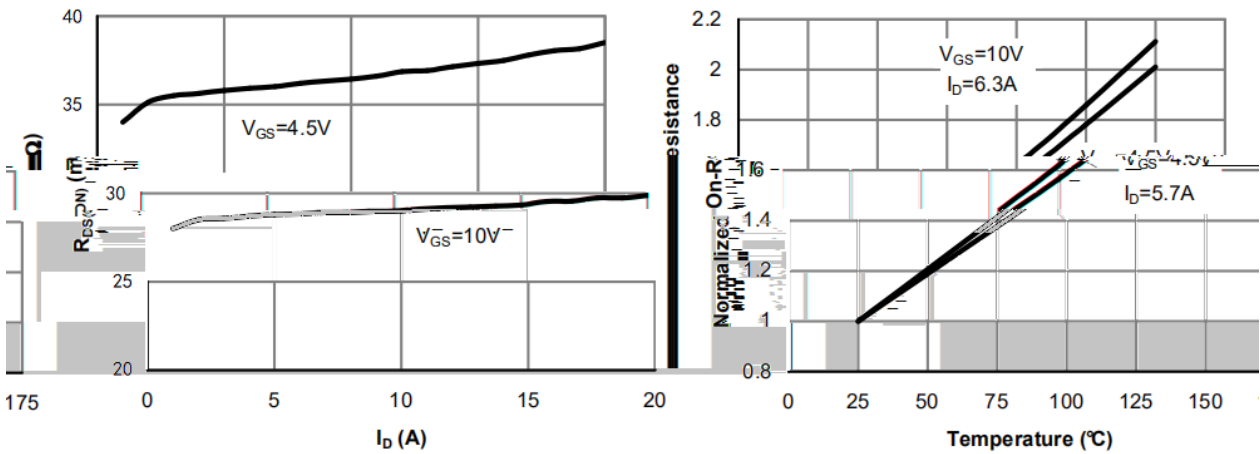


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

Figure 4: On-Resistance vs. Junction Temperature and Gate Voltage

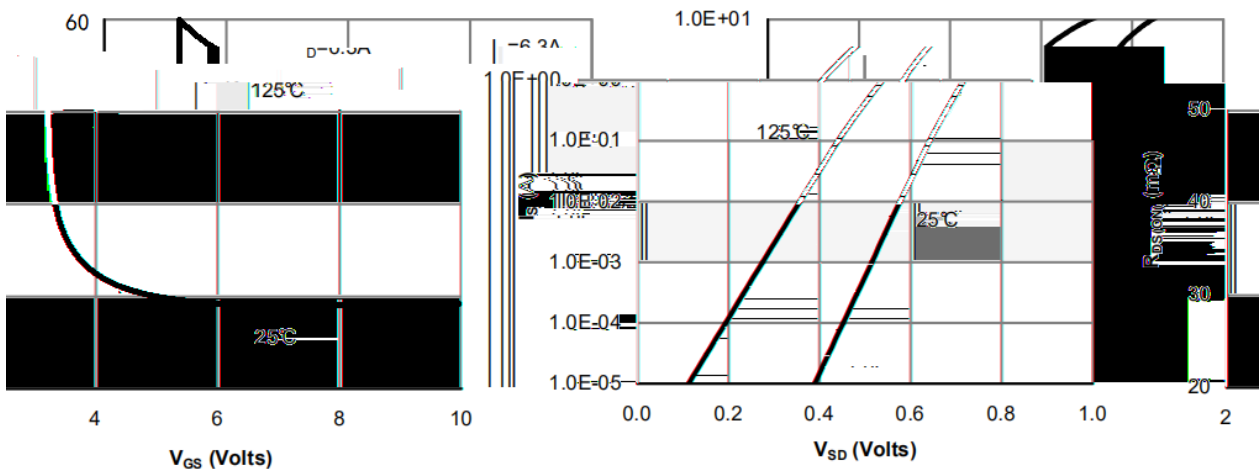


Figure 5: On-Resistance vs. Gate-Source Voltage

Figure 6: Body-Diode Characteristics

Fig

N-

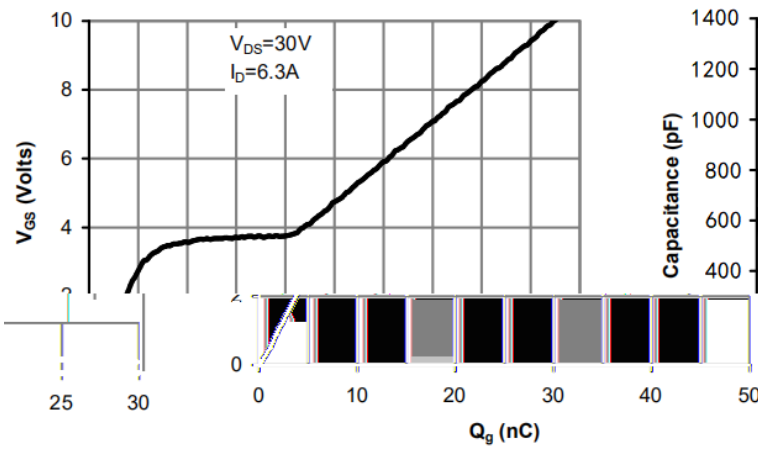


Figure 7: Gate-Charge Characteristics

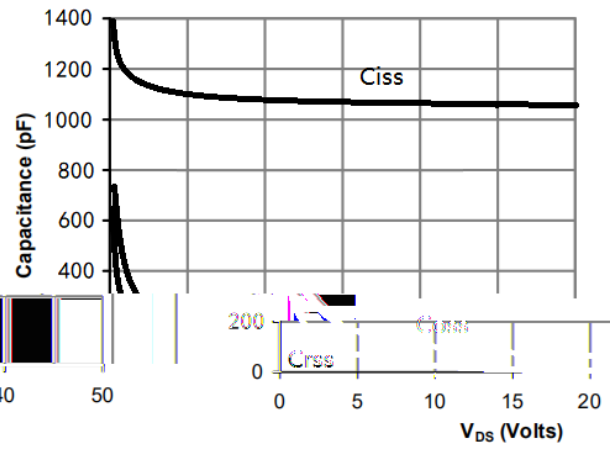


Figure 8: Capacitance Characteristics

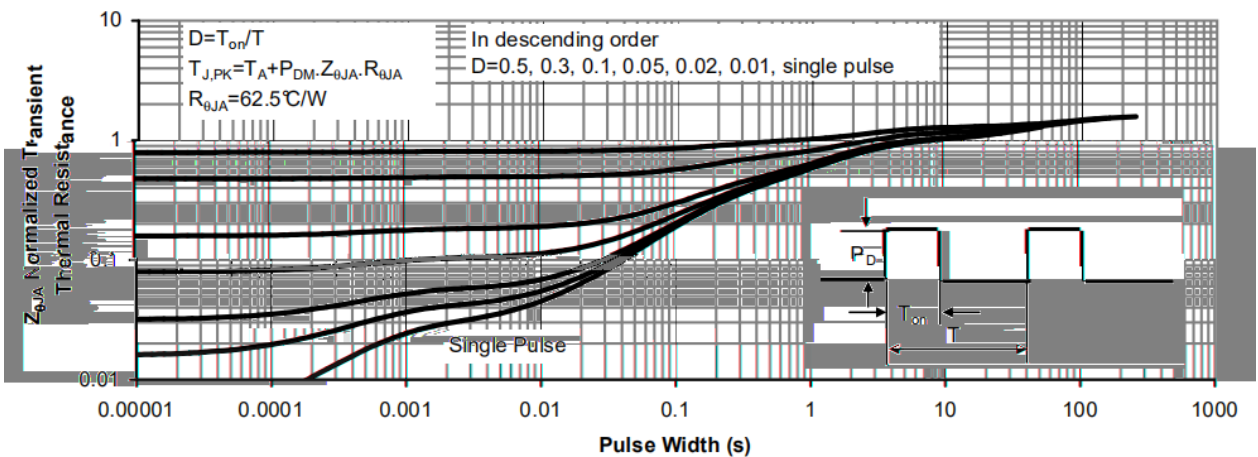
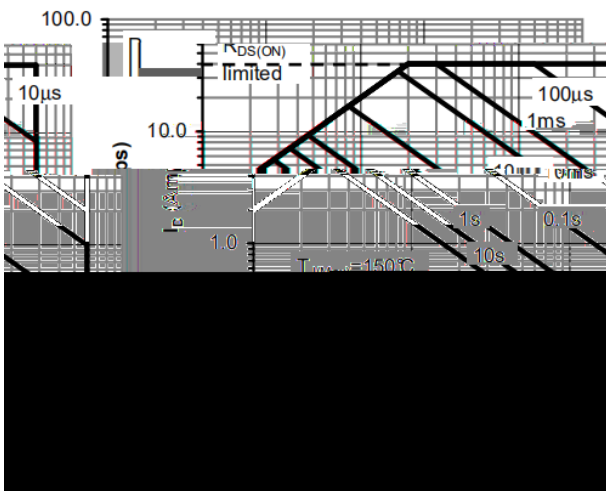
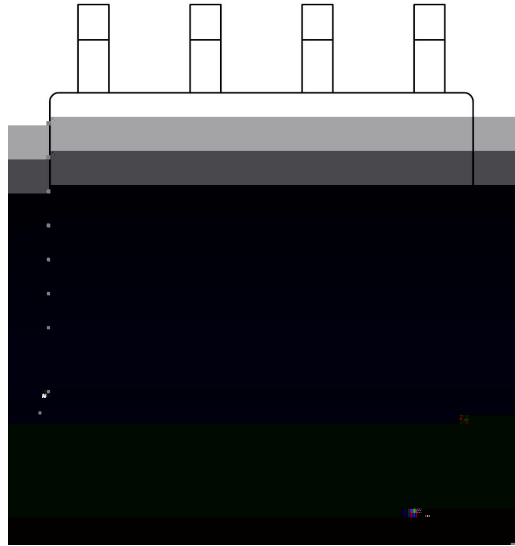


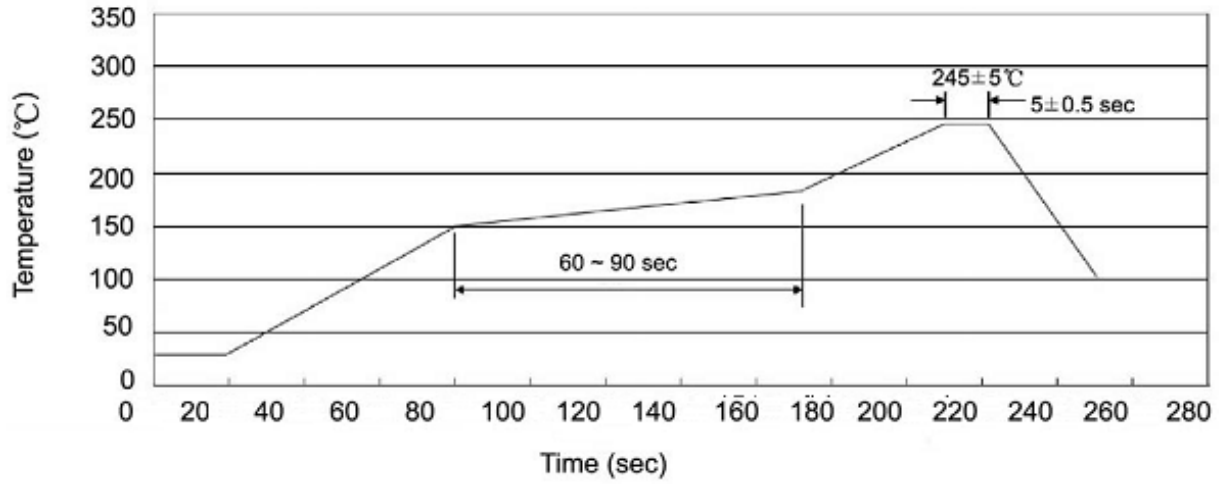
Figure 10: Normalized Maximum Transient Thermal Impedance

P-





Temperature Profile for IR Reflow Soldering (Pb-Free)



±

±

±

±

±

±

封装形式	包装数量					包装尺寸 :		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOP/ESOP-8	4,000	2	8,000	6	48,000	13" × 12	360×360×50	380×335×366